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Application Number				UNKNOWN 10/666,432	
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First Named Inventor				Vishwas V. Hardikar	
Group Art Unit				UNKNOWN 1742	
Examiner Name				UNKNOWN Leader	
Attorney Docket Number				004.0108	
Sheet	1	of	1		

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## OTHER ART

(Including Author, Title, Date, Pertinent Pages, Etc.)

W2		"Electrodeposition of Copper Thin Film on Ruthenium - A Potential Diffusion Barrier for CU Interconnects", Oliver Chyan et al., Journal of The Electrochemical Society, Volume 150, Number 5 (2003)
W2		"Seedless Superfill: Copper Electrodeposition in Trenches with Ruthenium Barriers", D. Josell et al., Electrochemical and Solid State Letters, June 5, 2003
W2		"Liner Materials for Direct Electrodeposition of Cu", M.W.Lane et al., Applied Physics Letter, Volume 83, Number 12, September 22, 2003
W2		"International Technology Roadmap for Semiconductors", 2001

William Leader 4/18/2007